507671099 12/29/2022

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
XUHUI PENG	06/14/2020
KERUI XI	06/14/2020
TINGTING CUI	06/14/2020
FENG QIN	06/14/2020
JIE ZHANG	06/14/2020

RECEIVING PARTY DATA

Name:	SHANGHAI TIANMA MICRO-ELECTRONICS CO., LTD.
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City:	SHANGHAI
State/Country:	CHINA
Postal Code:	200120
Name:	SHANGHAI AVIC OPTO ELECTRONICS CO.,LTD.
Name: Street Address:	SHANGHAI AVIC OPTO ELECTRONICS CO.,LTD. 3388TH HUANING RD, MINHANG DISTRICT
	·
Street Address:	3388TH HUANING RD, MINHANG DISTRICT

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18090918

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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PATENT REEL: 062237 FRAME: 0433

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ATTORNEY DOCKET NUMBER:	00189.0412.01US
NAME OF SUBMITTER:	JAY LI
SIGNATURE:	/Jay Li/
DATE SIGNED:	12/29/2022
Total Attachments: 3 source=oath00189041201#page1.tif source=oath00189041201#page2.tif source=oath00189041201#page3.tif	

PATENT REEL: 062237 FRAME: 0434

ASSIGNMENT AND DECLARATION

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

SEMICONDUCTOR PACKAGE AND FORMATION METHOD THEREOF for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on ______ (Application No. ______); and

WHEREAS, Shanghai Tianma Micro-Electronics Co., Ltd., a corporation of P.R. China whose post office address is 888, 889 Huiging Rd., Pudong New District, Shanghai, China 200120, and Shanghai AVIC OPTO Electronics Co., Ltd., a corporation of P.R. China whose post office address is 3388th Huaning Rd, Minhang District, Shanghai, China, 201108 (hereinafter referred to as Assignees), are desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. $\underline{18090918}$ filed $\underline{2022-12-29}$) the filing date and application number of said application when known.

Legal Name:

Signature:

Further, as a below named inventor, I hereby declare that: This declaration is directed to the application attached hereto or United States application or PCT international application number ______filed on _____ If the application is not attached hereto, the application is as identified above or by the attorney docket number as set forth above and/or the following. The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. I have reviewed and understand the contents of the above-identified application, including the claims. I acknowledge the duty to disclose information which is material to patentability as defined in Title 37,Code of Federal Regulations § 1.56, including for continuation-in-part applications, material information which became available between the filing data of the prior application and the national or PCT International filing date of the continuation-in-part application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both. IN TESTIMONY WHEREOF, I/We have hereunto set our hands. Inventor 1 Xuhui PENG Legal Name: Signature: Inventor 2 Kerui XI Legal Name: Signature: 2028.06.14 Inventor 3 Tingting CUI

Ting ting CUI

Date: 2020,06.74

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	Inventor 4 Legal Name:	Feng QIN			
1	Signature:	Eng Où		200.06.14	······································
``	Inventor 5 Legal Name:	Jie Zhang			
	Signature:	Thenhand	Date:		